

ABSTRACT OF THE DISCLOSURE

A modular heat-radiation structure includes a module 5 for generating heat, including a first main unit 5a having a fixing hole 5e and a lead 5L for connecting to the printed circuit board 3, a heat-radiation fin 7, fixed to the top face of the first main unit 5a, for radiating heat generated in the module 5, a resin-made and insulating heat shield 9 inserted between the printed circuit board 3 and the first main unit 5a, and a screw 13 for fixing the heat shield 9, the module 5, and the heat-radiation fin 7, where a lead hole 9L for allowing the lead 5L to pass therethrough and a first fixing hole 9e for allowing the screw 13 to pass therethrough are provided in the heat shield 9, and a second fixing hole 3e for allowing the screw 13 to pass therethrough is provided in the printed circuit board 3.